Willkommen bei O-Leading

O-Leading ist bestrebt, Ihr One-Stop-Lösungspartner in der EMS-Lieferkette zu sein, einschließlich Leiterplattendesign, Leiterplattenherstellung und Leiterplattenbestückung (PCB Assembly, PCBA) Wir können vom schnellen Drehungsprototyp zur mittleren u. Massenproduktion stützen.

Generell sind unsere globalen Kunden von unseren Dienstleistungen sehr beeindruckt: schnelle Reaktion, wettbewerbsfähiger Preis und Qualitätsverpflichtung. Die Bereitstellung von mehr wertvollem technischen Service und Gesamtlösung ist der Weg, den O nach vorne weist. Leiterplattenlieferant

Mit Blick auf die Zukunft wird sich O-Lead wie immer auf die Innovation und Entwicklung der Technologie für die Elektronikfertigung konzentrieren und beharrliche Anstrengungen unternehmen, um erstklassigen Service zu bieten und mehr Wert für unsere Kunden zu schaffen.

Wir sind professionelle PCB hersteller mit mehr als zehn jahren erfahrungen. Produktpalette: Einzel-, Doppelseiten-, Mehrschicht-Leiterplatten, flexible Leiterplatten und MCPCB. Wir bieten einen schnellen Prototypenservice - S / S in 24 Stunden, 4-8 Schichten in 48-96 Arbeitsstunden Produktionszeit.

KUPFERPLATTENLÖCHER MINDESTENS .025 AVG, .020 MIN .. LÖCHER DÜRFEN NICHT GESTOPFT WERDEN

Packung mit farbloser transparenter Luftpolsterfolie, 25 Stück / Beutel, Trockenmittel in die Flanke geben, Feuchtigkeitsanzeigekarte auf die Oberseite legen

Produktbeschreibung

Schichten: 2
Material: FR4
Fertige Dicke: 1,57 mm +/- 10%
Kupferschichtdicke: 1oz
Finish: ENIG (Au: 2-5u ")
Soldermask (Farbe): Beide Seiten, LPI (Schwarz)
Siebdruck (Farbe): Beidseitig, weiß

Elektrischer test

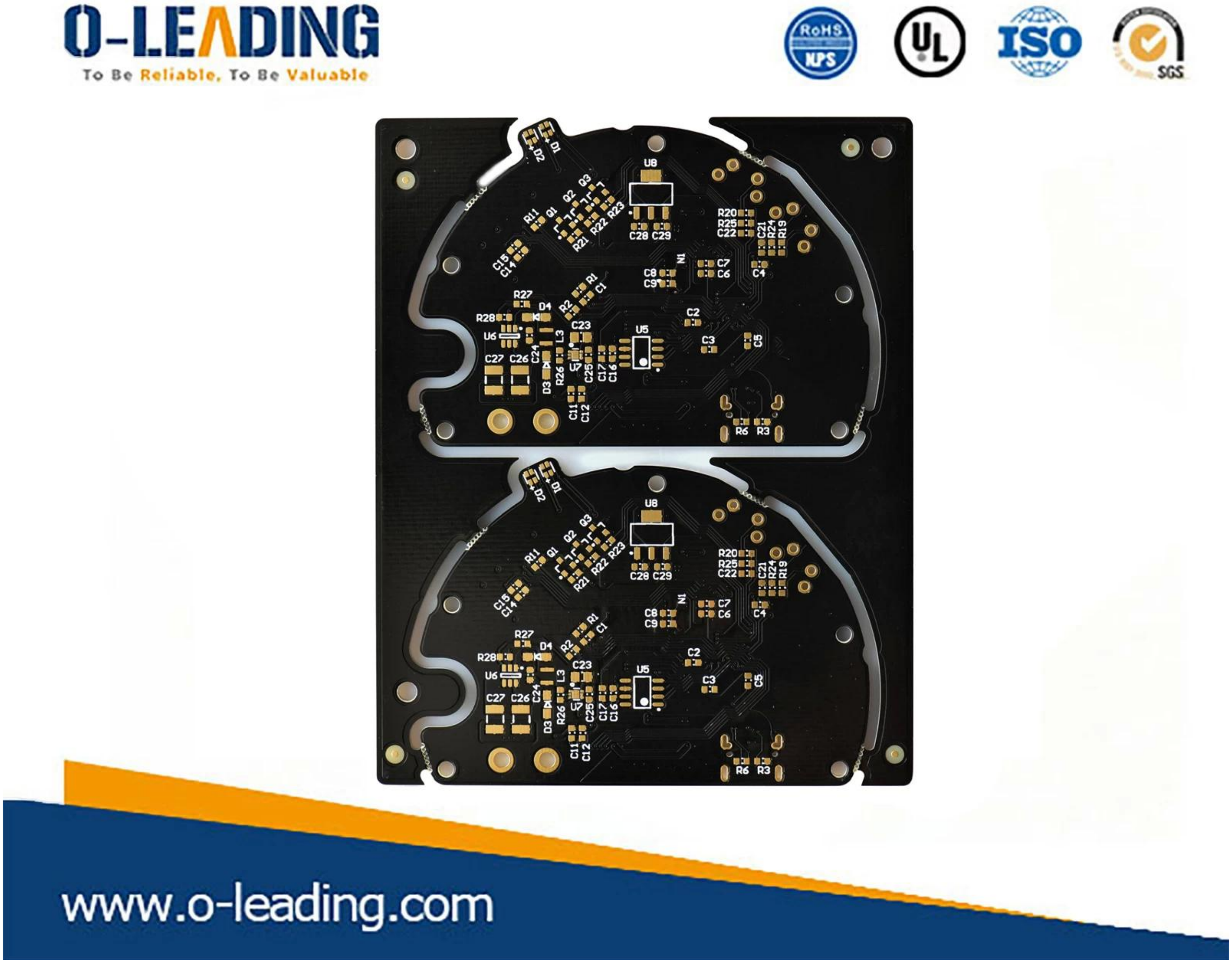
FINISH: DIESES BOARD IST NACH IPC-6012 IMMERSION VERGOLDET.
Die Dicke beträgt 0,050 um über 3 bis 6 um Nickel.

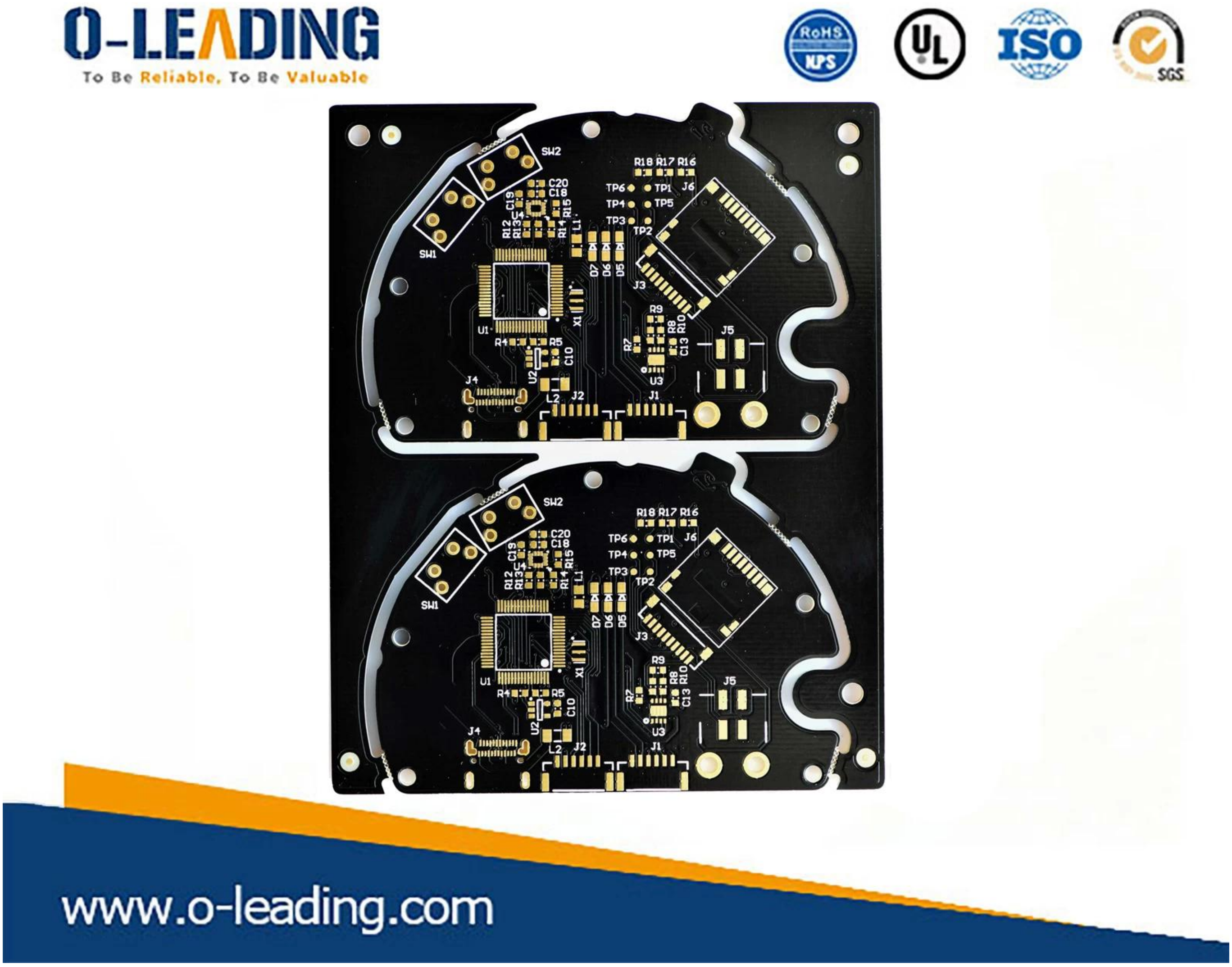
KUPFERPLATTENLÖCHER MINDESTENS .025 AVG, .020 MIN .. LÖCHER DÜRFEN NICHT GESTOPFT WERDEN, MIT AUSNAHME VON VIAS .500 FINISH ODER KLEINER.

Ebenenschlüssel:
==========
* .GM4: Board Outline
* .TXT: NC-Bohrdatei

* .GTP: Top Paste
* .GTO: Top-Siebdruck

* .GTS: Top Soldermask
* .GTL: Obere Kupferschicht
* .GBL: untere Kupferschicht
* .GBS: Bottom Soldermask
* .GBO: Unterer Siebdruck
* .GBP: Bottom Paste





Hochwertiger PCB-Großhandel

Unser Team


O-LEADING
To Be Reliable, To Be Valuable

Factory PCB

▼

Automatic vacuum press machine

▼

Drilling Machine

▼

Pattern Plating Machine

▼

Scrubbing Machine

▼

Developing Machine

▼

Routing Machine

▼

High-speed flying probe machine

▼

E-test Machine

Factory SMT

Zertifizierungen

CICC INSPECTION CERTIFICATION

CICC CERTIFICATION
嘉泰认证

QUALITY MANAGEMENT SYSTEM CERTIFICATE

Certificate No: 18118Q10347R05

We hereby certify that

O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED

Credit No: 61691591-000-07-18-7

Registration Add: FLAT/RM 1205 12/F TAI SANG BANK BUILDING 130-132 DES VOEUS BOAD CENTRAL HK

Business Add: 1313, Floor 13, Fortune Building, Danshui Town, Huiyang District, Huizhou, Guangdong, China

Has implemented and maintains a **Quality Management System**
Which fulfils the requirements of the following standards
GB/T19001-2016 idt ISO9001:2015

Scope of certification

Sales of printed circuit boards

Initial Issuance period: February 27, 2018
Renewal date: April 22, 2019
This certificate is valid during: April 22, 2019 ~ February 26, 2021
This certificate is invalid without CICC qualified label in the following period

First supervision and audit			Second supervision and audit	Qualified mark

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CICC INSPECTION CERTIFICATION

CICC CERTIFICATION
嘉泰认证

质量管理体系认证证书

证书号：18118Q10347R05

兹证明

诚领供应链（香港）有限公司

统一社会信用代码：61691591-000-07-18-7
注册地址：香港中環德輔道中130-132號大生銀行大廈1205室
经营地址：广东惠州惠阳淡水南亭西路财富大厦13楼1313

建立的质量管理体系符合

GB/T19001-2016 idt ISO9001:2015质量标准适用条款的要求

认证范围

印刷线路板的销售

初次获证日期：2018年02月27日
换证日期：2019年04月22日
证书有效期：自2019年04月22日至2021年02月26日
在下列期限内，未经CICC粘贴合格标贴，本证书无效

第一次监审			第二次监审	贴标处

本证书认证范围不包括未获得有效的国家规定的相关行政许可、资质许可的产品/服务范围。
本证书通过CICC定期监督审核保持，与年度《保持认证通知书》共同方为有效。
本证书信息可在国家认监委网站：www.cnca.gov.cn及CICC网站www.cicc-intl.com查询。

O-LEADING SUPPLY CHAIN (HK) CO.,LIMITED
1313,FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. :	RP19-005089 - SZ
Date of Sample Received :	22 Mar 2019
Testing Period :	22 Mar 2019 - 30 Mar 2019
Test Requested :	Selected test(s) as requested by client.
Test Method :	Please refer to next page(s).
Test Results :	Please refer to next page(s).
Conclusion :	Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP) , Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) , and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina

Tina Fan
Approved Signatory

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Attention: To check the authenticity of testing /inspection report & certificate, please contact us at telephone: (86-755) 8307 1443, or email: CN.Doccheck@sgs.com

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Test Results :

Test Part Description :

Specimen No.	**SGS Sample ID**	**Description**
SN1	SZX19-005304.001	Green"PCB"

Remarks :

(1) 1 mg/kg = 1 ppm = 0.0001%
(2) MDL = Method Detection Limit
(3) ND = Not Detected (< MDL)
(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017, IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	*001*
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	8
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (Cr(VI))	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tribromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tribromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND

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UL Product iQ™

ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD
ROOM 1205, 12/F
TAI SANG BANK BLDG
130-132 DES VOEUS ROAD
CENTRAL, HONG KONG

E490354

	Cond Width				Max			Max			
		Min	Cond	SS/	Area	Solder		Oper		Meets	C
	Min	Edge	Thk	DS/	Diam	Limits		Temp	Flame	UL796	T
Type	mm(in)	mm(in)	mic(mil)	DSO	mm(in)	C	sec	C	Class	DSR	I
Multilayer (mass laminate) printed wiring boards.											
O-LEADING-401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING-407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer printed wiring boards.											
O-LEADING-408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer printed wiring boards.											
O-LEADING-002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING-003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
O-LEADING-033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING-205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING-S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*
O-LEADING-S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲	*
O-LEADING-S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

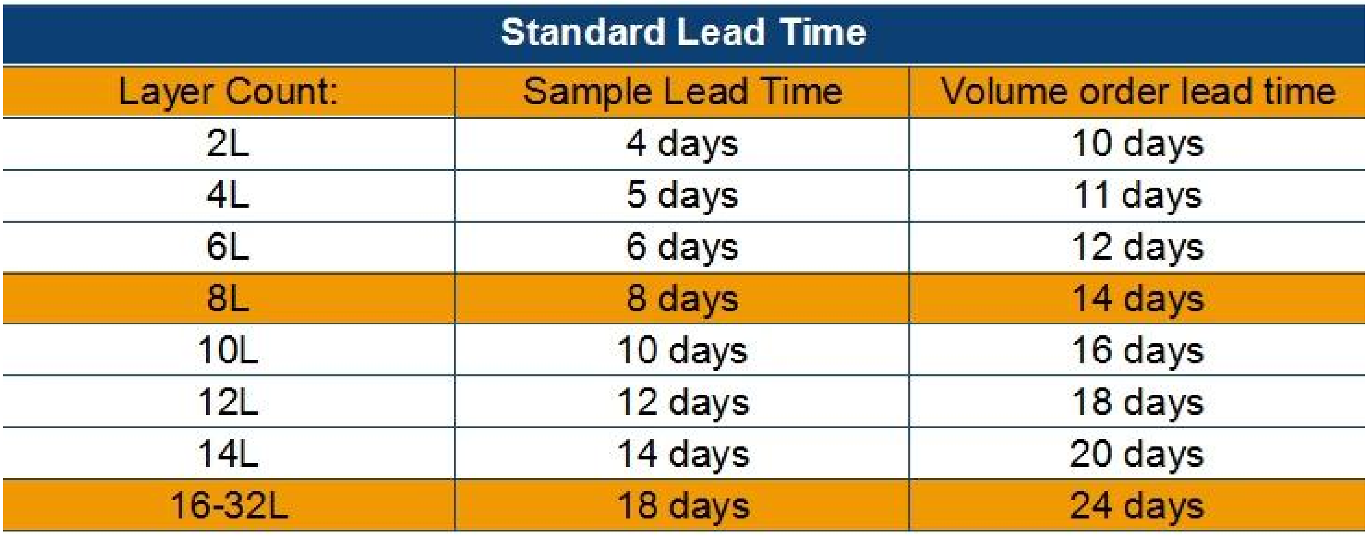
* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

Verpackung & Lieferung

Quick Turn Lead Time

Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA



Standard Lead Time

Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

Prozessfähigkeit

SMT-Produktionsmöglichkeiten

Leiterplattenmaterial: FR-4, CEM-1, CEM-3, Leiterplatte auf Aluminiumbasis
Maximale Leiterplattengröße: 510 x 460 mm
Min PCB Größe: 50x50mm
PWB-Stärke: 0.5mm-4.5mm
Brettstärke: 0.5-4mm
Min. Komponentengröße: 0201
Komponente mit Standardchipgröße: 0603 und größer
Maximale Höhe der Komponente: 15 mm
Min. Steigung: 0,3 mm
Min. BGA-Kugelpitch: 0,4 mm
Platzierungsgenauigkeit: +/- 0,03 mm